

Description

LISAT LST-TIP-3X1 Thermal Interface Pad is a highly compliant Thermal Pad material. It has excellent performance and a high thermal conductivity of 11 W/m-k. The Thermal Pad has a good wetting ability. It is able to achieve a low interface thermal impedance with normal pressure level. It is a product that is ideal for fragile components lead. A good recoverability provides rebounding force to ensure a reliable contact thus allowing effective thermal dissipation from heat source through filled gap by removing air to its best ability.



Features and Benefits

- Good & High Thermal Conductivity of 11.0 W/m-k
- Good Thermal Impedance
- Good Electrical Insulation
- Good Surface Wetting Properties
- Elasticity for Reliable Long Term Work
- Wide Thickness Range

Typical Applications

- @ Telecommunication Device
- @ CPU, GPU, VGA High Power Chips
- @ LED Heat Management Solution
- @ Solar Inverter Heat Solution
- @ Heat Component & Heat Sink
- @ IT Network Terminal

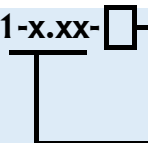
Properties

Note : Below technical data and information should be thought as typical or representative only and should not be use for specification purpose

TYPICAL PROPERTIES OF THERMAL INSULATOR LST-TIP-3X1

PROPERTY	METRIC VALUE	REFERENT STANDARD
Color	Gray	Visual
Density (g/cc)	3.5	ASTM D792
Thickness (mm)	0.5 ~ 5.0	ASTM D374
Hardness (Shore 00)	70	ASTMD2240
Continuous Use Temp (°F) / (°C)	-40 to +200	ASTM D5470
ELECTRICAL		
Dielectric Breakdown Voltage (KV/mm)	≥ 5	ASTM D149
Volume Resistivity (Ω-cm)	10 x 10 ¹¹	ASTM D257
Flame Rating	UL94	UL94
THERMAL		
Thermal Conductivity (W/m-K)	11.0	ASTM D5470

Part-Number Ordering System : LST-TIP-3X1-x.xx-



Blank = Non Adhesive

AC = Adhesive Coated

Standard Thickness =

0.50 / 1.00 / 1.50 / 2.00 /
2.50 / 3.00 / 3.50 / 4.00 /
4.50 / 5.00 mm

LISAT

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